



Sony SI-F209 SMT Pick And Place Machine for Substrate Size 50mm*50mm-460mm*360mm Maximum Load 1800KG

Our Product Introduction

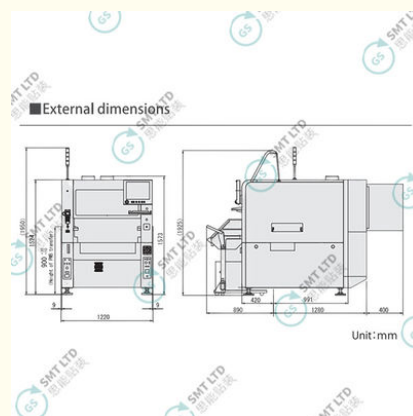
Basic Information

- Place of Origin: Japan
- Brand Name: Sony
- Model Number: SI-F209
- Minimum Order Quantity: 1 PCS
- Price: USD+negotiable+pcs
- Packaging Details: 1350*1850*1650mm
- Delivery Time: 1-7 days
- Payment Terms: T/T
- Supply Ability: 1+pcs+per days



Product Specification

- Model: Sony SI-F209
- Substrate Size: 50mm*50mm-460mm*360mm
- Substrate Thickness: 0.5mm to 2.6mm
- Number Of Mounting Heads: 1 Head 6 Nozzles
- Mounting Range: 2012(0804)-32mmIC
- Component Height: Max 7mm Mobile Camera Fixed Camera 25mm
- Mounting Speed: 0.49sec(7350CPH)
- Mounting Accuracy: 60um (CPK1.0 Or Above) Chip
- Power Supply: AC3-phase 200V±10% 50/60HZ
- Power Consumption: 2.3kw
- Gas Consumption: 0.49MPA 100L/min
- Appearance Size: 1220mm*1700mm*1573mm
- Weight: 1800KG
- Machine Size: 1350*1850*1650mm



Product Description

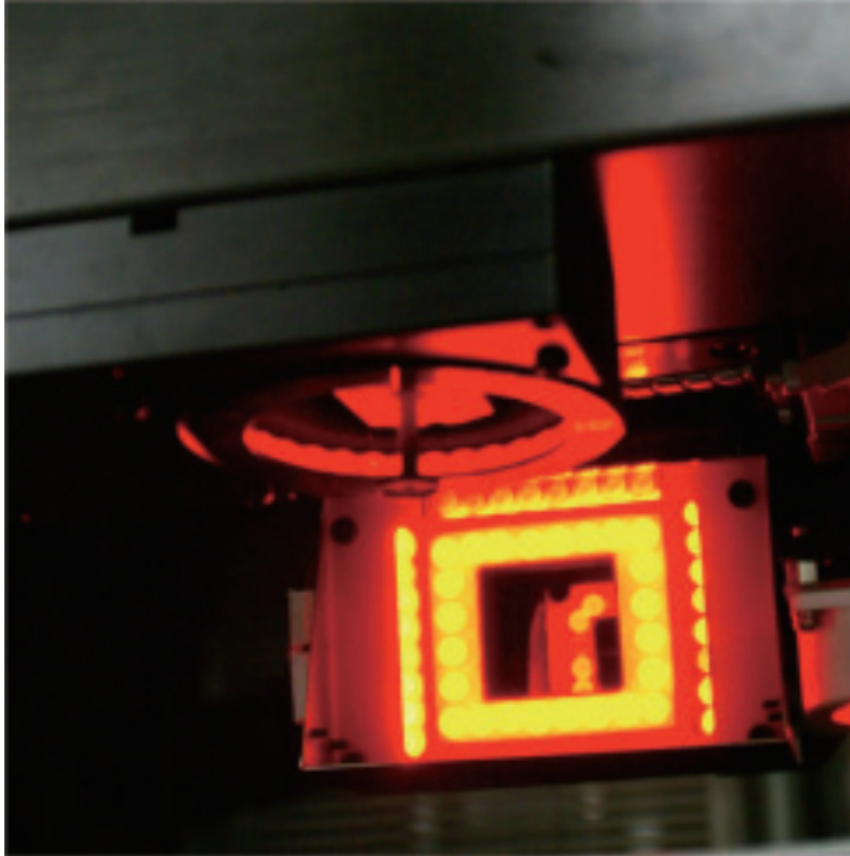
Description:

Enhance your PCB assembly with the Sony SI-F209, a cutting-edge SMT mounter renowned for its precision and high-speed capabilities. ●With a robust modular design that allows for rapid reconfiguration, this machine is an ideal solution for electronics manufacturers seeking to maximize productivity and reduce placement costs. ●It boasts an adaptable feeder system capable of handling a diverse array of components, ensuring seamless integration into any SMT line. ●The SI-F209's advanced vision system guarantees exact alignment and placement, driving efficiency even for complex boards. ●Rely on Sony's innovation to meet the demanding standards of modern SMT production with this versatile mounter.

Electronic Part Mounter SI-F209:

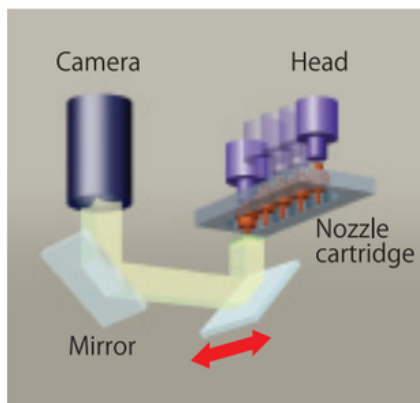
1.Supports large, odd-shaped parts

The unit is equipped with a multifunction head that is capable of mounting parts ranging from size 2012 to $\phi 150\text{mm}$. The unit also automatically corrects the pick up position on the parts to improve the pick up rate.

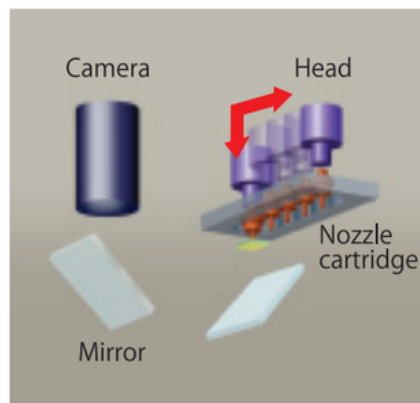


2.Reduces loss in tact time

To increase productivity, the unit features flying vision and flying nozzle change functions, which respectively perform parts recognition and nozzle changes while the head is in motion after picking up or placing parts.



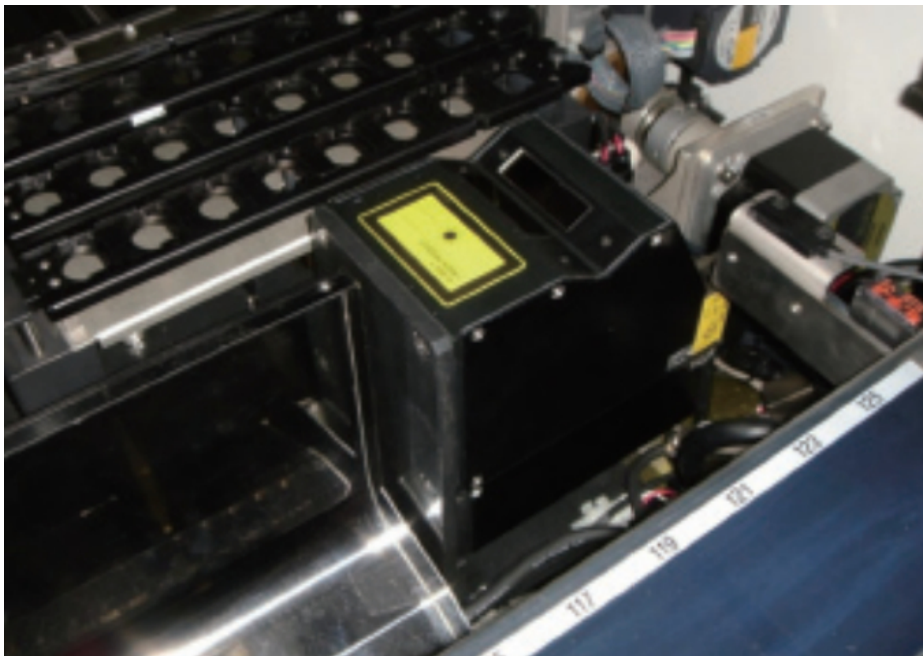
Flying vision



Flying nozzle change

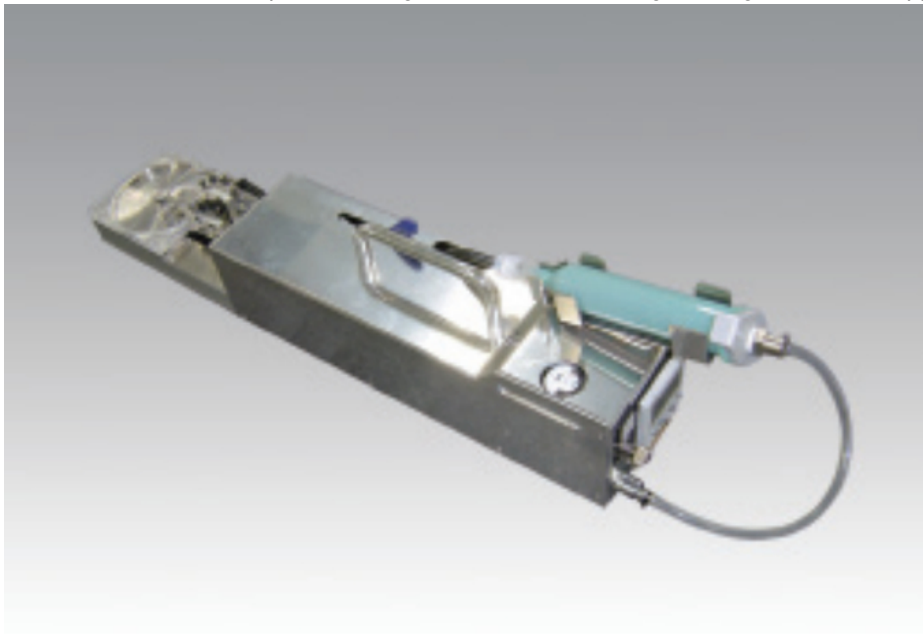
3.Coplanarity system*

This system inspects leads and solder balls of the large parts such as QFP and BGA.



4.Dip Unit*

This is a flux and solder paste coating unit for POP mounting.Coating material is supplied automatically.



5.PDX(Product Explorer)*

Receives and distributes production data and performs device management at will. Improves your productivity, traceability and quality levels through remote machine control.



6.CPS Pro 4*

This software optimizes the layout of nozzles and parts supply on all the SI series. Equipped with the same GUI as the unit's display, it is even easier to use.

